

PRODUCT SPECIFICATION

Product Name	AI7697HD MT7697D IoT SiP Module
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AcSiP Technology Corp.
An IoT Solution Company

3F,-1 No.207,Fusing Rd., Taoyuan City,Taoyuan Dist.,Taoyuan City 33066, Taiwan(R.O.C)
T. +886 3 286-8388 F. +886 3 347-5000 www.acsip.com.tw

Document History

Date	Revised Contents	Revised by	Version
Nov 23 rd ,2016	Initial Version	Kevin	A
Apr 10 th ,2017	Operation temp. range modified	Chunyi	B
Dec 12 th ,2017	802.11a band modified	Ivan	C
Aug 14 th ,2018	Add FCC/CE information in POD and Product Marking	Ivan	D

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1. Description

AcSiP Technology Corp. introduces a low-cost and low-power consumption IoT module. This stand-alone module is an operating system designed for wearable or internet of things (IoT) devices with smart connection and cloud application/services.

AI7697HD is a highly integrated SIP module which features an application processor, a low power 1x1 dual-band Wi-Fi subsystem, a Bluetooth subsystem, and a Power Management Unit. The application processor subsystem contains an ARM Cortex-M4F MCU, which has many peripherals, including UART, I2C, SPI, I2S, PWM, IrDA, and auxiliary ADC. AI7697HD also includes embedded SRAM/ROM and an external 4MB serial flash.

The Wi-Fi subsystem contains the 802.11a/b/g/n radio, baseband, and MAC that are designed to meet both the low power and high throughput application. It also contains a 32-bit RISC CPU that could fully offload the application processor.

The Bluetooth subsystem contains the Bluetooth radio, baseband, link controller. It also uses the same 32-bit RISC CPU for the Bluetooth protocols.

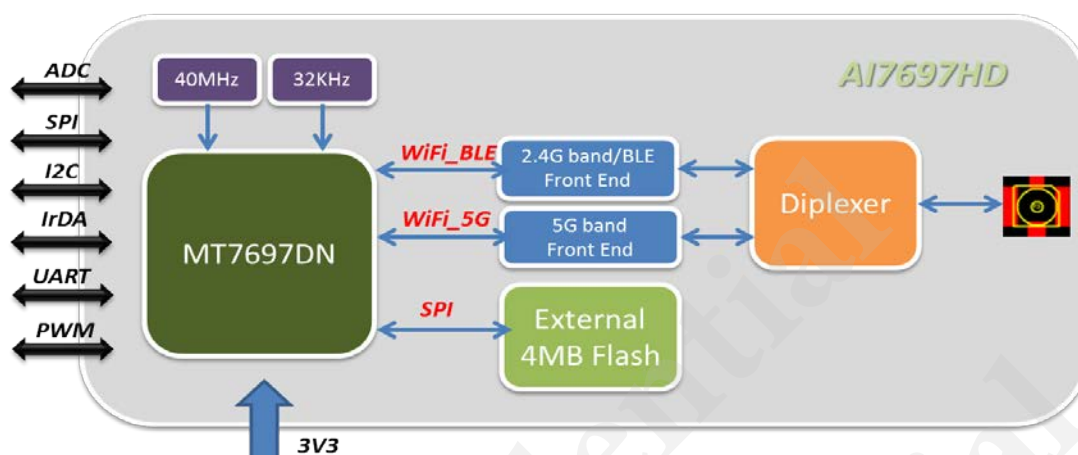
1.1. Platform Features

General

- ARM Cortex M4 MCU with FPU with up to 192MHz clock speed
- 352KB SRAM / 64KB boot / 4MB Flash
- Supports external serial flash with Quad Peripheral Interface (QPI) mode
- Supports eXecute In Place (XIP) on flash
- 32KB cache in XIP mode
- Hardware crypto engines including AES, DES/3DES, SHA2 for network security
- Two UART interfaces with hardware flow control and one UART for debug, all multiplexed with GPIO
- One SPI slave interface multiplexed with GPIO
- Two I2C master interface multiplexed with GPIO
- One I2S interface multiplexed with GPIO
- Four channel 12-bit ADC multiplexed with GPIO
- Dedicated high-performance 32-bit RISC CPU N9 up to 160MHz clock speed
- IEEE 802.11 a/b/g/n compliant
- Supports 20MHz,40MHz bandwidth in 2.4/5GHz
- Dual-band 1T1R mode with data rate up to 150Mbps
- Supports STBC, LDPC
- Greenfield, mixed mode, legacy modes support
- IEEE 802.11 d/e/h/i/k/r/w support
- Security support for WFA WPA/WPA2 personal, WPS2.0, WAPI
- Supports 802.11w protected managed frames
- QoS support of WFA WMM, WMM PS
- Integrated LNA, PA, and T/R switch
- Optional external LNA and PA support.
- RX diversity support with additional RX input
- Bluetooth 4.2 Low Energy (LE)



2. Block Diagram



2.1. Specification

AI7697HD	
Chipset	MT7697D
Core	ARM Cortex-M4 MCU
FPU Clock Speed	192MHz
SRAM	352KB
External Flash	4MB
Antenna connector	MHF4 series: 20449-001E
Support 5G Band(MHz)	5150~5250(Band1) 、 5250~5350(Band2) 5470~5725(Band3) 、 5725~5850(Band4) 、 5850~5925
Operation Condition	
Temperature	Operating : -40℃ ~ +85℃ Storage : -40℃ ~ +105℃
Humidity	Operating : 10 ~ 95% (Non-Condensing) Storage : 5 ~ 95% (Non-Condensing)
Mechanical Information	
Dimension	18mm X 18mm X 1.7mm (Typ.)
Package	LGA 44Pin – Stamp hole type
Certification	
FCC ID	2ADWC-AI7697HD
CE	EN300328 / EN301489 / EN60950-1 / EN301893 / RED (CE_Radio) / EMF

3. Electrical Characteristics

3.1. Absolute Maximum Ratings

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{BAT}	Supply Voltage	3	3.3	3.6	V
I/O Voltage	I/O supply voltage	3	3.3	3.6	V

3.2. RF Characteristics

3.2.1. RF Characteristics for 802.11b 11M

802.11b Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Tx Power Level	DQPSK	18.0	20.0	22.0	dBm
Frequency Tolerance		-15	0	15	ppm
Spectral Mask	11MHz→22MHz		40		dBr
	> 22MHz		53		dBr
Modulation Accuracy	All Data Rate		15		%
802.11b Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	11Mbps PER<8%	-90	-88	-86	dBm

3.2.2. RF Characteristics for 802.11g 54M

802.11g Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Tx Power Level	OFDM	15.0	17.0	19.0	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All data rate		-31	-28	dB
802.11g Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	54Mbps PER<10%	-77.0	-75.0	-73.0	dBm

3.2.3. RF Characteristics for 802.11n MCS7(HT20)

802.11n_HT20 Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency range		Channel 1		Channel 13	
Tx Power Level	OFDM	15.0	17.0	19.0	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All Data Rate		-31	-28	dB
802.11n_HT20 Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	MCS7 PER<10%	-75	-73	-71	dBm

3.2.4. RF Characteristics for 802.11n MCS7(HT40)

802.11n_HT40 Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency range		Channel 1		Channel 13	
Tx Power Level	OFDM	15.0	17.0	19.0	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All Data Rate		-30	-28	dB
802.11n_HT40 Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	MCS7 PER<10%	-73.5	-71.5	-69.5	dBm

3.2.5. RF Characteristics for 5G 802.11n MCS7(HT20)

5G 802.11n_HT20 Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency range		5180		5825	MHz
Tx Power Level	OFDM	11.0	13.0	15.0	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All Data Rate		-29	-28	dB
5G 802.11n_HT20 Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		5180		5825	MHz
Min. Input	MCS7 PER<10%	-72	-70	-68	dBm

3.2.6. RF Characteristics for 5G 802.11n MCS7(HT40)

5G 802.11n_HT40 Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency range		5180		5825	MHz
Tx Power Level	OFDM	10.0	13.0	14.0	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All Data Rate		-29	-28	dB
5G 802.11n_HT40 Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	MCS7 PER<10%	-69	-67	-65	dBm

3.2.7. RF Characteristics for 5G 802.11a 54M

5G 802.11a Transmit (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		5180		5825	MHz
Tx Power Level	OFDM	12.0	14	16.0	dBm
Frequency Tolerance		-15	0	15	ppm
Modulation Accuracy	All data rate		-29	-28	dB
5G 802.11a Receiver (Conductive)					
Item	Condition	Min.	Typ.	Max.	Unit
Frequency Range		Channel 1		Channel 13	
Min. Input	54Mbps PER<10%	-74.0	-72.0	-70.0	dBm

3.2.8. Bluetooth LE Receiver Specifications

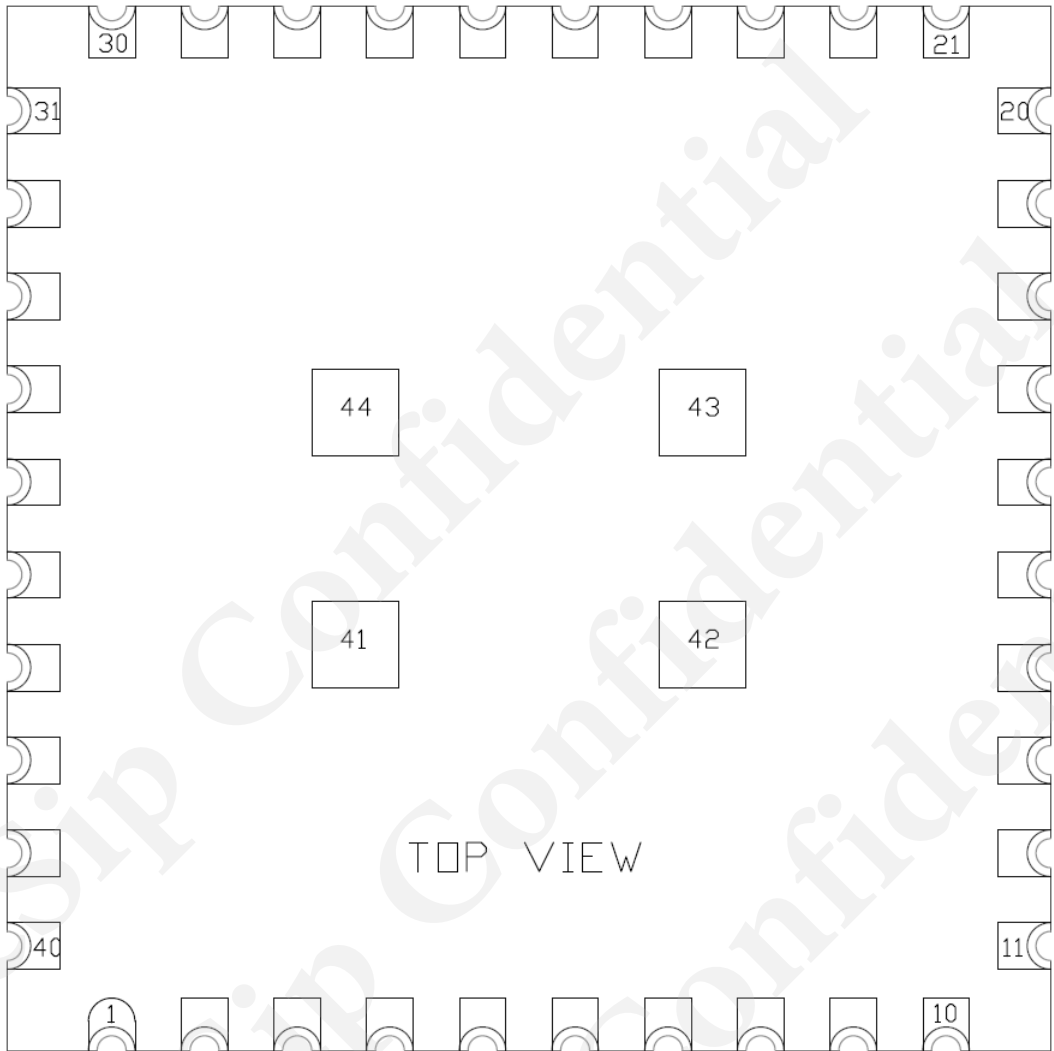
Parameter	Description	Min.	Typ.	Max.	Unit
Frequency Range		2402		2480	MHz
Receiver Sensitivity	PER<30.8%		-93		dBm
Max. Usable Signal	PER<30.8%	-9	-5		dBm
C/I Co-channel	Co-channel selectivity (PER<30.8%)		6	21	dB
C/I 1MHz	Adjacent channel selectivity (PER<30.8%)		-7	15	dB
C/I 2MHz	2 nd Adjacent channel selectivity (PER<30.8%)		-30	-17	dB
C/I >=3MHz	3 rd Adjacent channel selectivity (PER<30.8%)		-33	-27	dB
C/I Image channel	Image channel selectivity (PER<90.8%)		-20	-9	dB
C/I Image 1MHz	1MHz adjacent to image channel selectivity (PER<30.8%)		-30	-15	dB
Inter-modulation		-50	-35		dBm
Out-of-band Blocking	30MHz to 2000MHz	-30			dBm
	2001MHz to 2339MHz	-35			dBm
	2501MHz to 3000MHz	-35			dBm

3.2.9. Bluetooth LE Transmitter Specifications

Parameter	Description	Min.	Typ.	Max.	Unit
Frequency Range		2402		2480	MHz
Output Power	At max power output level	-21	5	9	dBm
Carrier Frequency Offset and Drift	Frequency offset	-150		150	KHz
	Frequency drift	-50		50	KHz
	Max. drift rate	-20		20	Hz/us
Modulation Characteristic	Δf_{1avg}	225		275	KHz
	Δf_{2max} (For at least 99% of all Δf_{2max})	185			KHz
	$\Delta f_{1avg}/\Delta f_{1avg}$	0.8	0.94		Hz/Hz
In-band Spurious Emission	$\pm 2M$ offset			-20	dBm
	$>\pm 3M$ offset			-30	dBm

4. Pin Definition

4.1. Detailed Pin Description

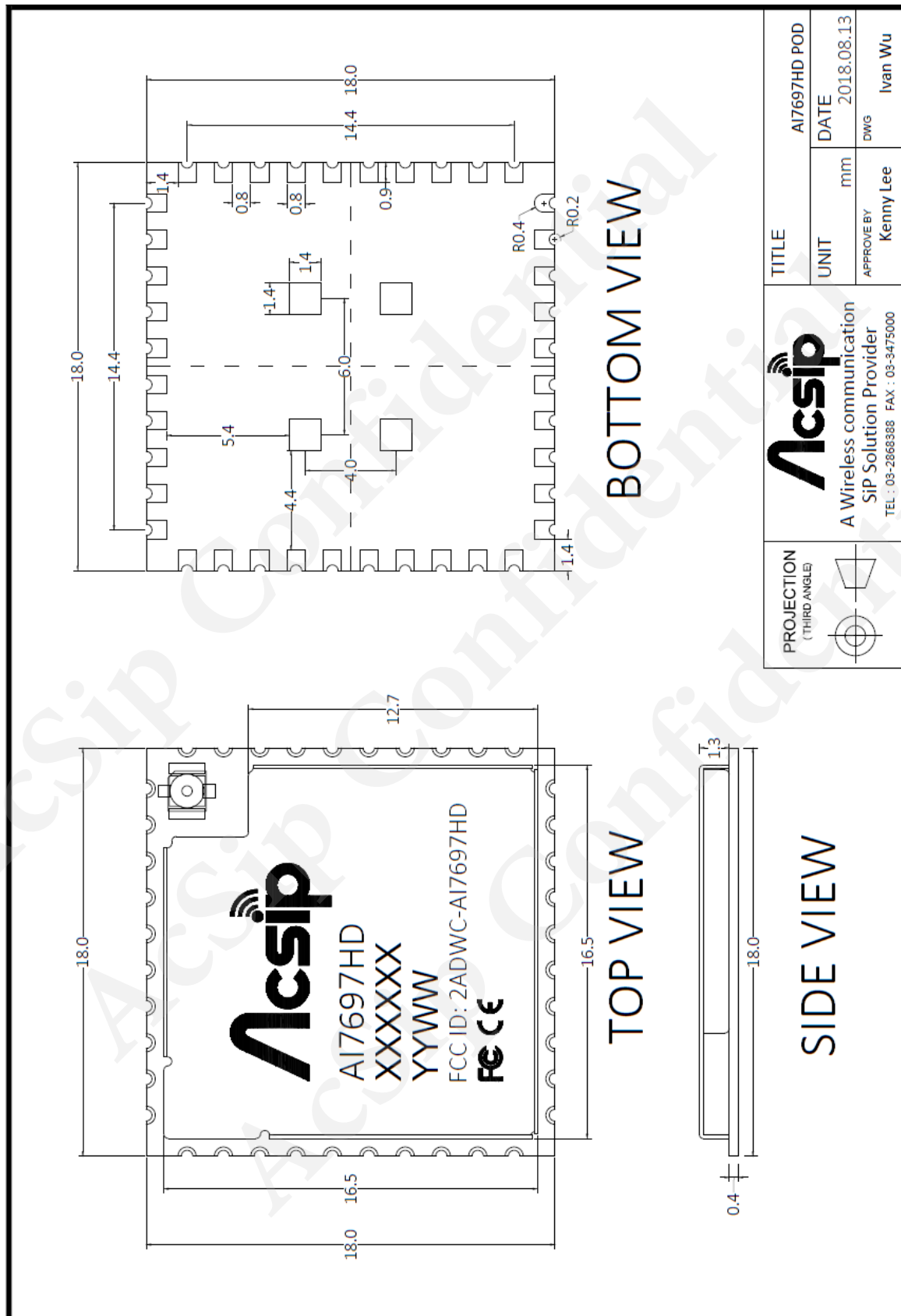


PIN no.	Pin Name	PIN no.	Pin Name
1	GPIO29	23	GPIO0
2	GPIO30	24	GPIO1
3	GPIO28	25	GPIO2
4	GPIO27	26	GPIO3
5	PMU_EN_WF	27	GPIO6
6	GPIO60	28*	SPI_CS
7	GPIO59	29*	SPI_DO
8	GPIO58	30*	SPI_WP
9	GPIO57	31*	SPI_HOLD
10	GPIO39	32*	SPI_CLK
11	SYS_RST_N	33*	SPI_DI
12	GPIO38	34	RTC_3V3
13	GPIO37	35	GND
14	3V3	36	PMU_EN_RTC
15	GPIO36	37	GPIO32
16	GPIO35	38	GPIO31
17	GPIO34	39	3V3
18	GPIO33	40	GND
19	GND	41	Thermal GND
20	NC	42	Thermal GND
21	GND	43	Thermal GND
22	GND	44	Thermal GND

* Please refer to "AI76x7H series PINMUX Table.pdf" file for more information about pin configuration.

* It's important to notice that Pin28~33 are also connected to the module internal flash. Be mindful when you perform operation with them. If customers need not these pins, please let them in DNC.

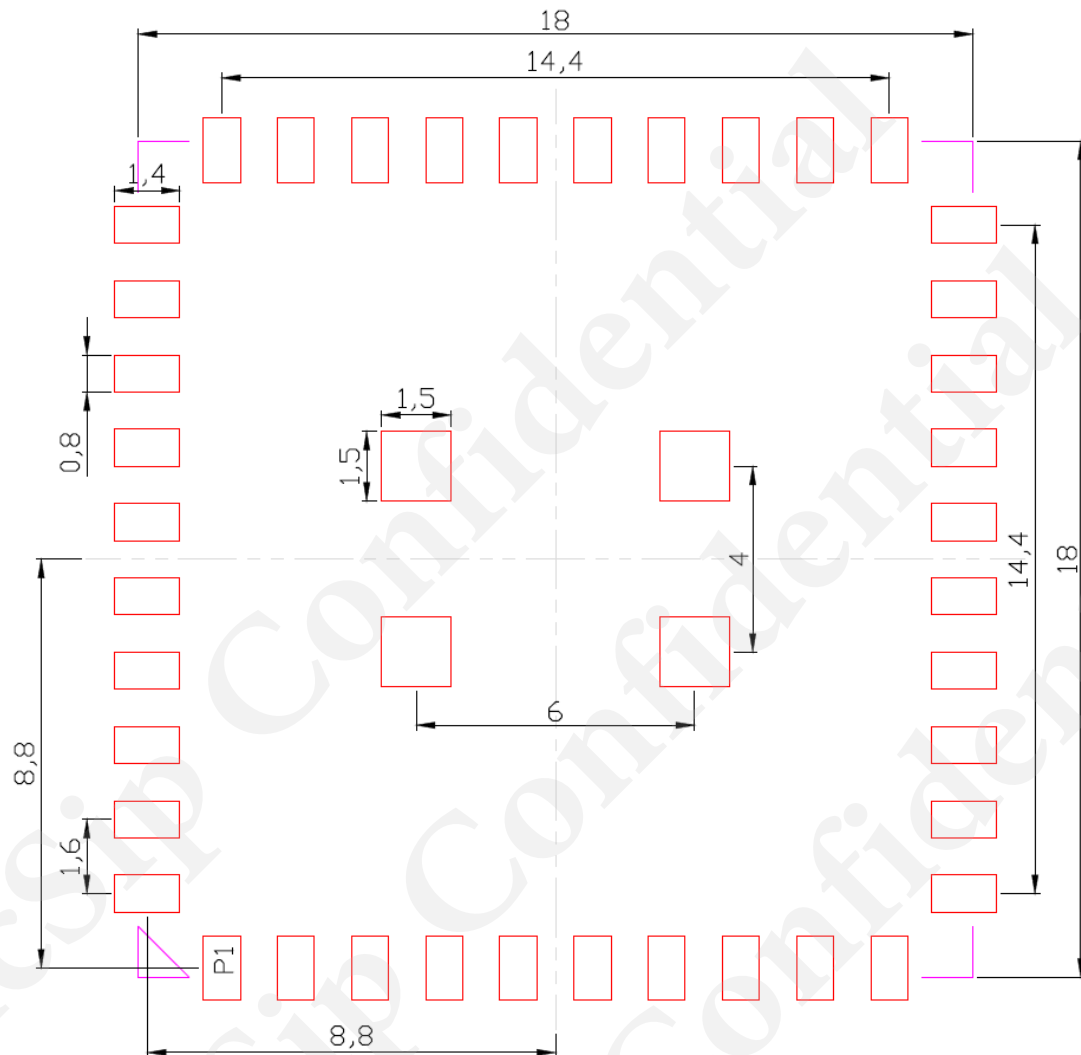
4.2. AI7697HD POD Information



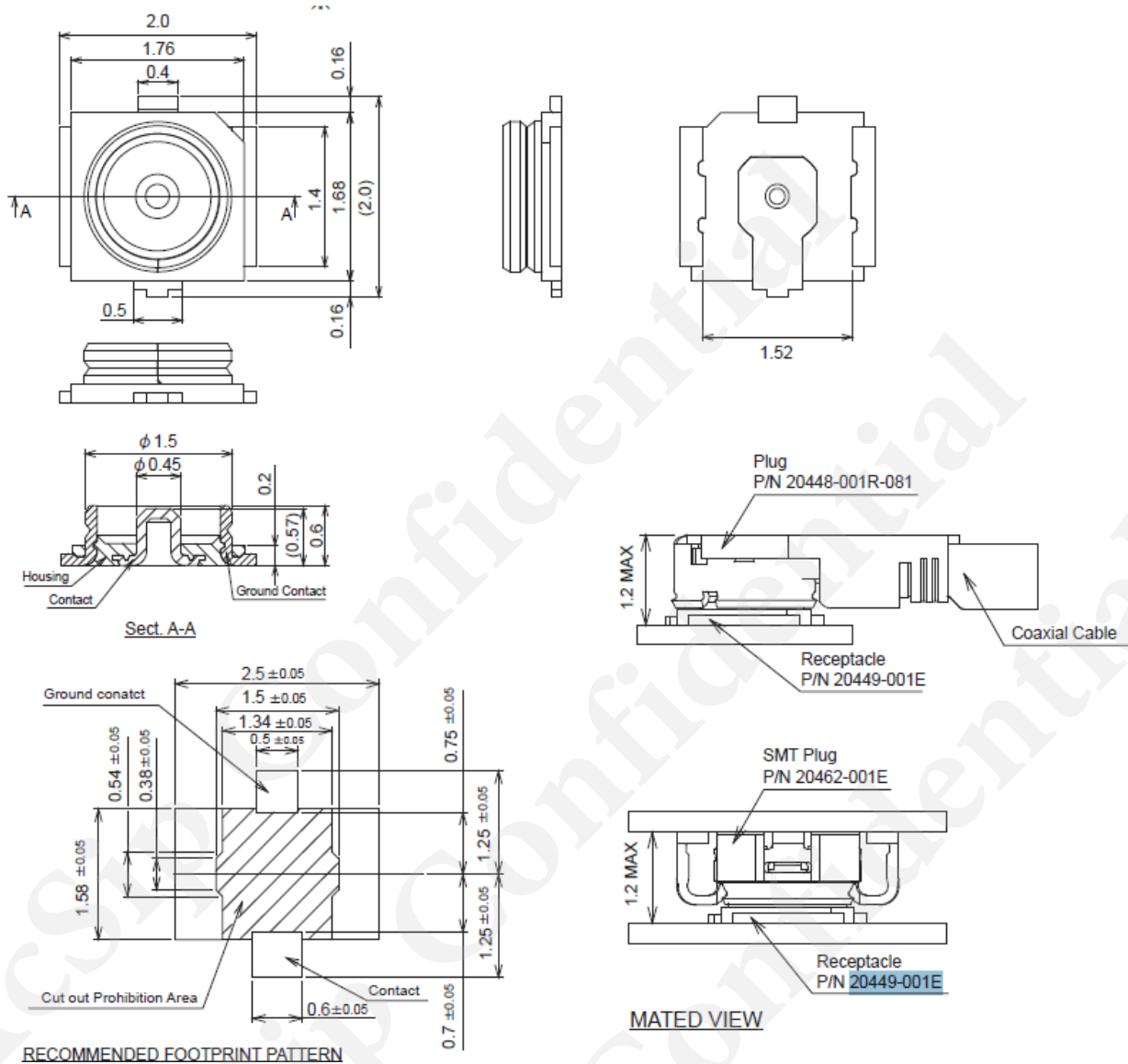
Recommended PCB Landing

UNIT : mm

TOPVIEW



4.3. Antenna Connector Dimension



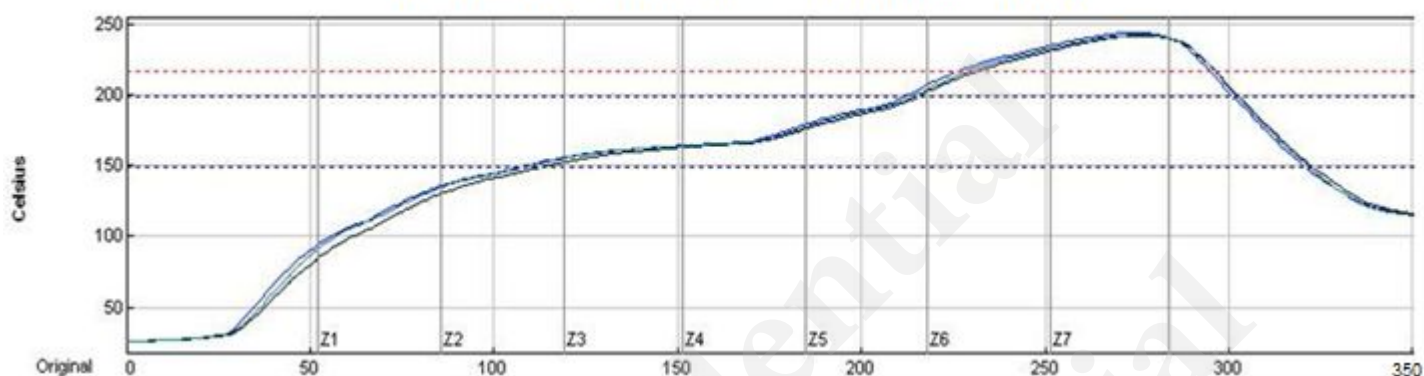
5. Regulator

This SiP module is passed on module level to comply with following standards:

- FCC ID : 2ADWC-AI7697HD
- CE : EN300328 / EN301489 / EN60950-1 / EN301893 / RED (CE_Radio) / EMF

6. Recommended Reflow Profile

Reflow Profile for SiP on board Assembly



Preheat time	150°C—200°C : 105+/-15sec
Dwell time	Over 220°C : 70+5/-10 sec
Peak Temp	240 +10/-5°C
Ramp Up/Down Rate	Up: 3 +0/-2 °C / sec Down: 2 +0/-1°C / sec

7. SiP Module Preparation

7.1. Handling

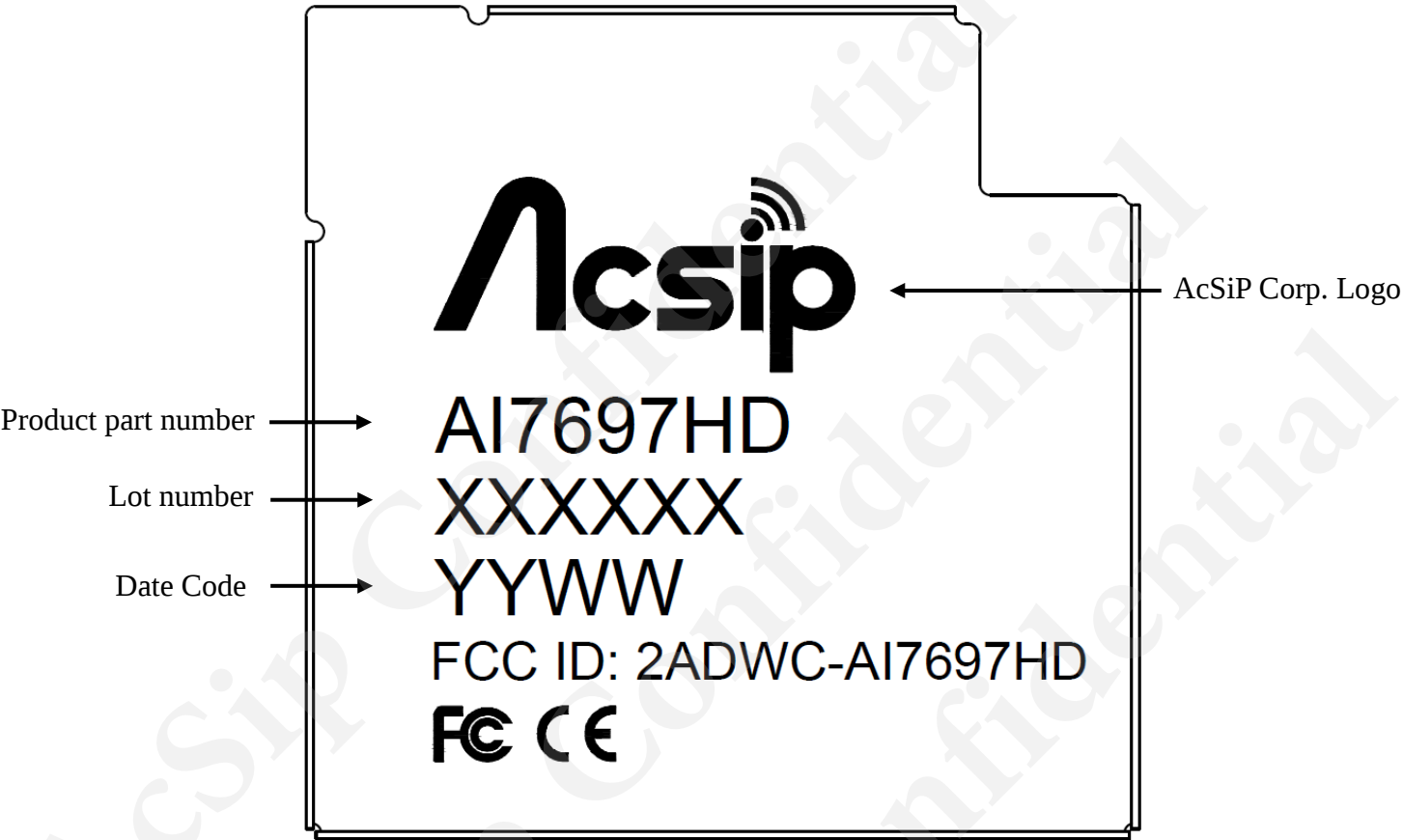
Handling the module must wear the anti-static wrist strap to avoid ESD damage. After each module is aligned and tested, it should be transport and storage with anti -static tray and packing. This protective package must be remained in suitable environment until the module is assembled and soldered onto the main board.

7.2. SMT Preparation

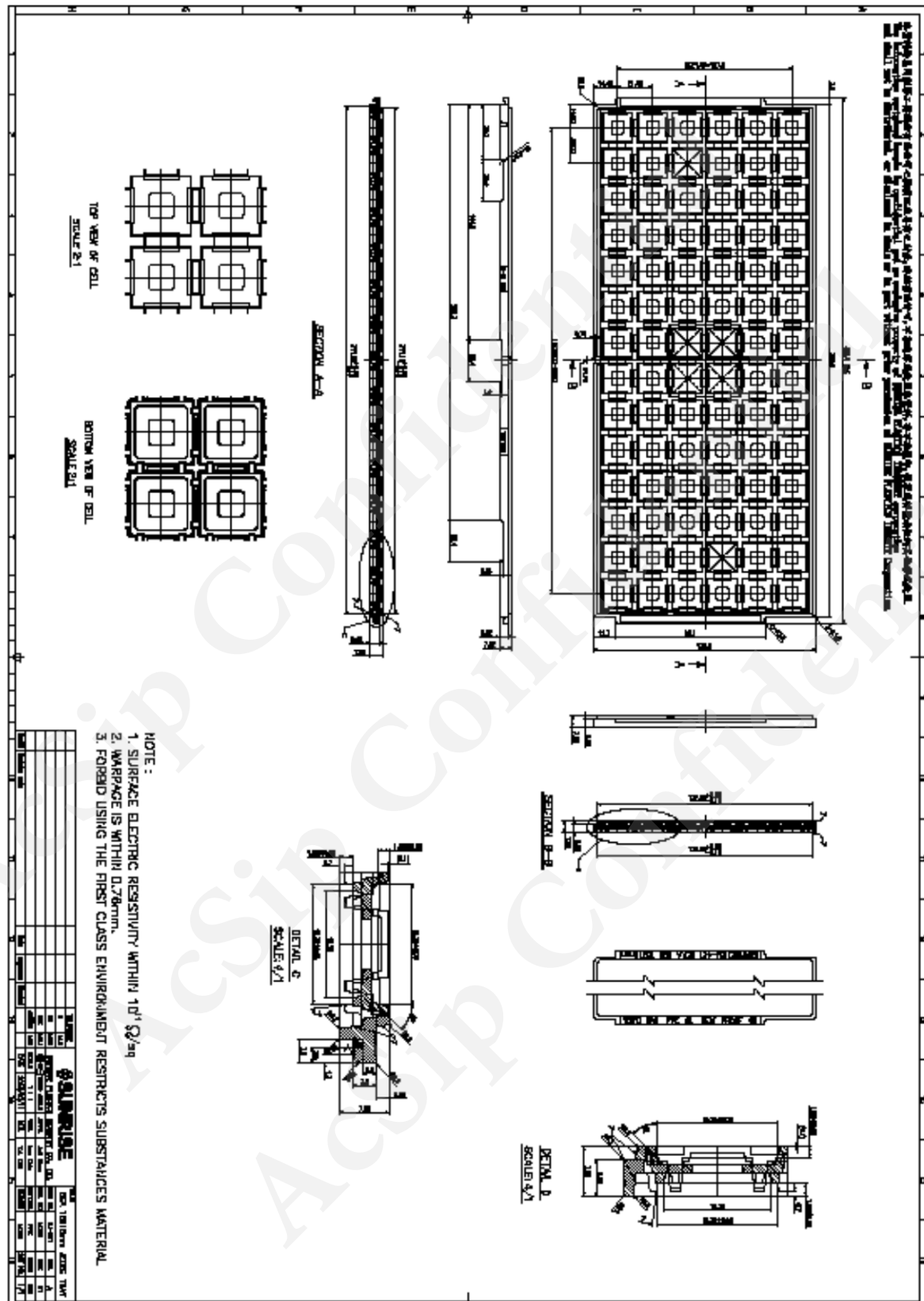
1. Calculated shelf life in sealed bag: 6 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH).
2. Peak package body temperature: 250°C .
3. After bag was opened, devices that will be subjected to reflow solder or other high temperature process must.
 - A. Mounted within: 168 hours of factory conditions $<30^{\circ}\text{C}/60\%\text{RH}$.
 - B. Stored at $\leq 10\%\text{RH}$ with N2 flow box.
4. Devices require baking, before mounting, if:
 - A. Package bag does not keep in vacuumed while first time open.
 - B. Humidity Indicator Card is $>10\%$ when read at $23\pm 5^{\circ}\text{C}$.
 - C. Expose at 3A condition over 8 hours or Expose at 3B condition over 24 hours.
5. If baking is required, devices may be baked for 12 hours at $125\pm 5^{\circ}\text{C}$.

8. Package Information

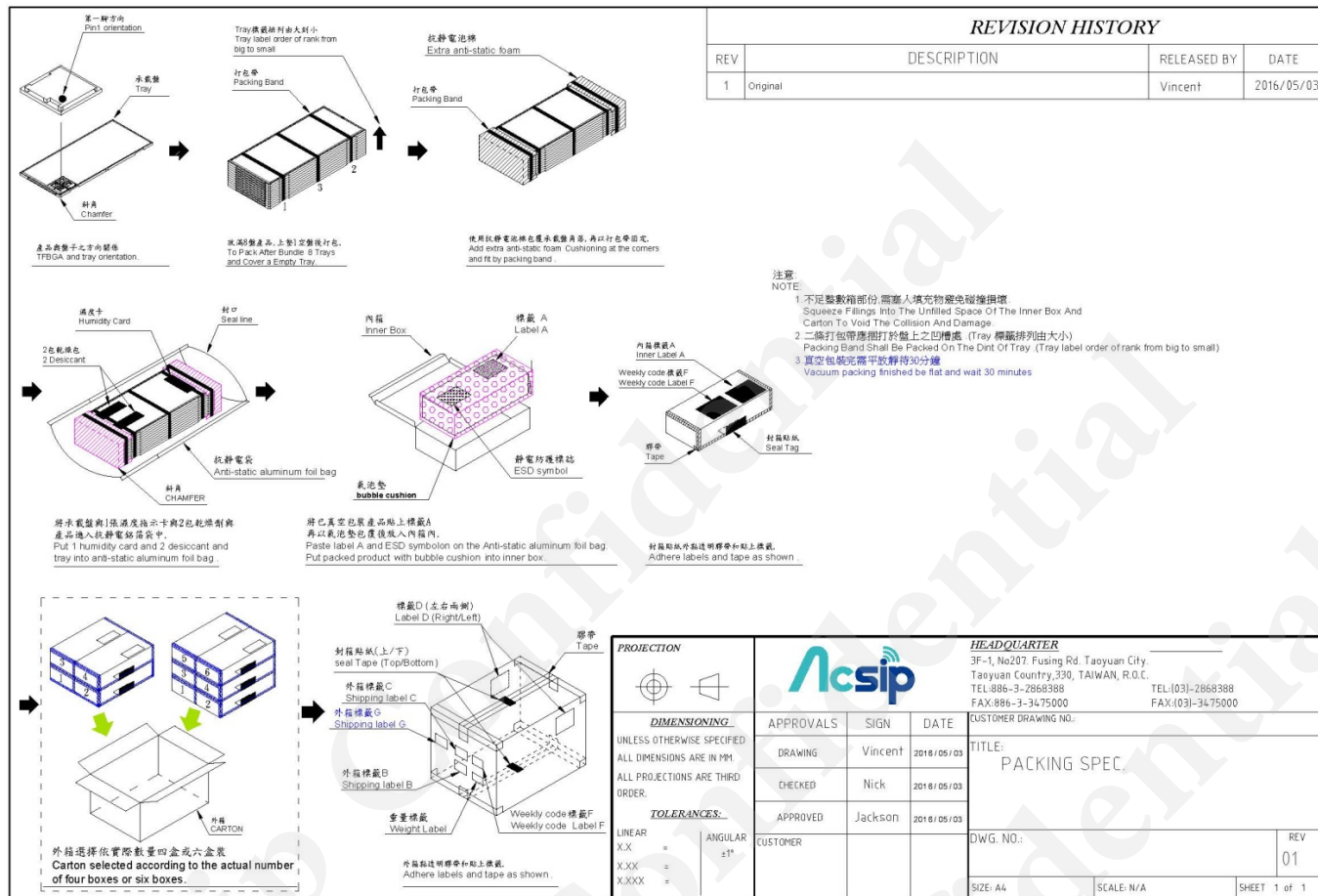
8.1. Product Making



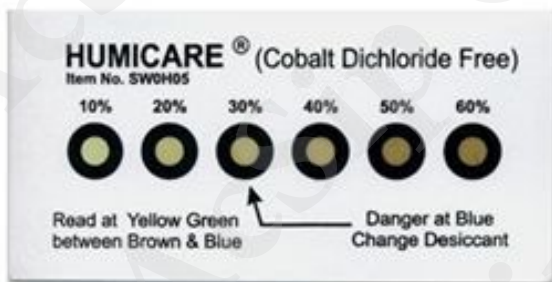
8.2. Tray Dimension



8.3. Packing Information



8.4. Humidity Indicator Card



Dry

Indicates 指示點:

10%,20%,30,40%,50%,60% relative humidity

10%,20%,30,40%,50%,60% 相對濕度

Color Change 顏色變化:

Brown (Dry) ---> Blue (Wet)

棕色 (乾燥) → 藍色 (潮溼)



Wet